



			DB	Time stamp
L	Hits	Search Text		
Number		linking! on DCD	USPAT;	2003/03/24
1	20704	"double side polishing" or DSP	EPO; JPO;	15:22
			IBM TDB	
İ		onbo) bee the teritory of	USPAT;	2003/03/24
2	2183	(grinding or grind or grinded) and (edge	EPO; JPO;	15:53
		or circumference) and (polished or	IBM TDB	13.33
]		polishing or polish) and etch\$3	USPAT;	2003/03/24
3	30	("double side polishing" or DSP) and	EPO; JPO;	15:24
		((grinding or grind or grinded) and (edge	IBM TDB	13.2.
		or circumference) and (polished or	IBM_IDB	
		polishing or polish) and etch\$3)	USPAT;	2003/03/24
4	432	(grinding or grind or grinded) and (edge	EPO; JPO;	16:02
		or circumference) and (polished or	IBM TDB	10.02
		polishing or polish) and etch\$3 and	1014_100	
		(testing of testedor metrology)	USPAT;	2003/03/24
5	52	((grinding or grind or grinded) and (edge	EPO; JPO;	16:00
		or circumference) and (polished or	IBM TDB	1 10.00
		polishing or polish) and etch\$3 and	1BM_1DB	
		(testing of testedor metrology)) and		1
		438/\$.ccls.	USPAT;	2003/03/24
6	192	((grinding or grind or grinded) and (edge	EPO; JPO;	16:00
		or circumference) and (polished or	IBM TDB	13333
		polishing or polish) and etch\$3 and	1011_100	
		(testing of testedor metrology)) and		
		semiconductor	USPAT;	2003/03/24
7	271	(grinding or grind or grinded) and (edge	EPO; JPO;	16:52
		or circumference) and (polished or	IBM TDB	
		polishing or polish) and etch\$3 and	12122	
		(cluster or module)	USPAT;	2003/03/24
9	1	6309279.pn.	EPO; JPO;	16:50
			IBM TDB	
		(grinding or grind or grinded) and (bevel	USPAT;	2003/03/24
11	13	or beveling) and (polished or polishing	EPO; JPO;	16:54
1	-	or beveling) and (polished of polishing or polish) and etch\$3 and (cluster or	IBM TDB	
		or polish) and econys and (claster of	_	
	146	module) (grinding or grind or grinded) and (bevel	USPAT;	2003/03/24
12	146	or beveling) and (polished or polishing	EPO; JPO;	16:58
		or polish) and etch\$3	IBM TDB	
	30	DCD\	USPAT;	2003/03/24
13	30	and (grinding or grind or grinded) and	EPO; JPO;	17:01
		(clean or cleaning or rinse or rinsing)	IBM TDB	
		and (polished or polishing or polish) and	_	
		etch\$3		
1	1	ELCI142		